



Part Number : [1704320001](#)
Product Description : zQuad Small Form Factor Pluggable Plus (zQSFP+) Assembly, Surface Mount, 38 Circuits, Gold (Au) Plated 0.381µm, Supports QSFP28 / EDR / QSFP56
Series Number : 170432
Status : Active
Product Category : High-Speed I/O Connectors



Documents & Resources

Drawings

[1704320001 sd.pdf](#)
[1704320001-PK-000.pdf](#)

3D Models and Design Files

[STEP AP242](#)
[SOLIDWORKS](#)
[Creo](#)
[Symbol and Footprint \(Multi-Format\)](#)
[SYM-170432-002-001.zip](#)
[1704320004-000.pdf](#)
[EE-170432-0004-001.pdf](#)
[1704320001-000.zip](#)
[SP-170432-0004-001.zip](#)

Specifications

[AS-170432-0002-001.pdf](#)
[PS-170432-001-001.pdf](#)
[TS-170432-0004-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	

	per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)4165-DC (25 June 2025)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	170432
Description	zQuad Small Form Factor Pluggable Plus (zQSFP+) Assembly, Surface Mount, 38 Circuits, Gold (Au) Plated 0.381µm, Supports QSFP28 / EDR / QSFP56
Application	Board-to-Board, Module-to-Board, Wire-to-Board
Comments	QSFP28 / EDR / QSFP56
Component Type	Receptacle
Product Name	zQSFP Plus,zQSFP+
Type	Pluggable

UPC	884982584310
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Agency

UL	E29179
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Electrical

Current - Maximum per Contact	0.5A
Data Rate	28.0 Gbps, 56.0 Gbps
Grounding to Panel	Yes
Voltage - Maximum	30V AC (RMS)

Physical

Circuits (Loaded)	38
Color - Resin	Black
Durability (mating cycles max)	50
Flammability	94V-0
Gender	Female
Keying to Mating Part	None
Lock to Mating Part	None
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	1.200/g
Number of Rows	1
Orientation	Right Angle
Packaging Type	Embossed Tape on Reel
Panel Mount	N/A
PCB Retention	Yes
Pitch - Mating Interface	0.80mm
Plating min - Mating	0.381µm
Polarized to Mating Part	N/A
Ports	1
Termination Interface Style	Surface Mount

Solder Process Data

Lead-Free Process Capability	N/A
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Mates With / Use With

Mates with Part(s)

Description	Part Number
zQSFP+-to-zQSFP+ Cable Assemblies	<u>100297</u>
QSFP+-to-QSFP+ Cable Assemblies	<u>111040</u>
QSFP+ Universal Loopback Adapters	<u>74763</u>

Use with Part(s)

Description	Part Number
zQSFP+ 1-by-1 Cage Assemblies with Spring Fingers	<u>100014</u>